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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	eZ8
Core Size	8-Bit
Speed	20MHz
Connectivity	IrDA, UART/USART
Peripherals	Brown-out Detect/Reset, LED, LVD, POR, PWM, WDT
Number of I/O	17
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8f041ahh020eg

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Table 3. Pin Characteristics (20- and 28-pin Devices)

Symbol Mnemonic	Direction	Reset Direction	Active Low or Active High	Tristate Output	Internal Pull-up or Pull-down	Schmitt- Trigger Input	Open Drain Output	5 V Tolerance
AVDD	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
AVSS	N/A	N/A	N/A	N/A	N/A	N/A	N/A	NA
DBG	I/O	I	N/A	Yes	Yes	Yes	Yes	No
PA[7:0]	I/O	I	N/A	Yes	Programma- ble Pull-up	Yes	Yes, Programma- ble	PA[7:2] unless pul- lups enabled
PB[7:0]	I/O	I	N/A	Yes	Programma- ble Pull-up	Yes	Yes, Programma- ble	PB[7:6] unless pul- lups enabled
PC[7:0]	I/O	I	N/A	Yes	Programma- ble Pull-up	Yes	Yes, Programma- ble	PC[7:3] unless pul- lups enabled
RESET/ PD0	I/O	I/O (defaults to RESET)	Low (in Reset mode)	Yes (PD0 only)	Programma- ble for PD0; always on for RESET	Yes	Programma- ble for PD0; always on for RESET	Yes, unless pul- lups enabled
VDD	N/A	N/A	N/A	N/A			N/A	N/A
VSS	N/A	N/A	N/A	N/A			N/A	N/A

Note: PB6 and PB7 are available only in those devices without ADC.

Table 8. Reset and Stop Mode Recovery Characteristics and Latency

	Reset Characteristics and Latency					
Reset Type	Control Registers	eZ8 CPU	Reset Latency (Delay)			
System Reset	Reset (as applicable)	Reset	66 Internal Precision Oscillator Cycles			
System Reset with Crystal Oscillator Enabled	Reset (as applicable)	Reset	5000 Internal Precision Oscillator Cycles			
Stop Mode Recovery	Unaffected, except WDT_CTL and OSC_CTL registers	Reset	66 Internal Precision Oscillator Cycles + IPO startup time			
Stop Mode Recovery with Crystal Oscillator Enabled	Unaffected, except WDT_CTL and OSC_CTL registers	Reset	5000 Internal Precision Oscillator Cycles			

During a System Reset or Stop Mode Recovery, the Internal Precision Oscillator requires 4 µs to start up. Then the Z8 Encore! XP F082A Series device is held in Reset for 66 cycles of the Internal Precision Oscillator. If the crystal oscillator is enabled in the Flash option bits, this reset period is increased to 5000 IPO cycles. When a reset occurs because of a low voltage condition or Power-On Reset (POR), this delay is measured from the time that the supply voltage first exceeds the POR level. If the external pin reset remains asserted at the end of the reset period, the device remains in reset until the pin is deas-serted.

At the beginning of Reset, all GPIO pins are configured as inputs with pull-up resistor disabled, except PD0 (or PA2 on 8-pin devices) which is shared with the reset pin. On reset, the PD0 is configured as a bidirectional open-drain reset. The pin is internally driven low during port reset, after which the user code may reconfigure this pin as a general purpose output.

During Reset, the eZ8 CPU and on-chip peripherals are idle; however, the on-chip crystal oscillator and Watchdog Timer oscillator continue to run.

Upon Reset, control registers within the Register File that have a defined Reset value are loaded with their reset values. Other control registers (including the Stack Pointer, Register Pointer and Flags) and general-purpose RAM are undefined following Reset. The eZ8 CPU fetches the Reset vector at Program Memory addresses 0002H and 0003H and loads that value into the Program Counter. Program execution begins at the Reset vector address.

As the control registers are reinitialized by a system reset, the system clock after reset is always the IPO. The software must reconfigure the oscillator control block, such that the correct system clock source is enabled and selected.

Shared Debug Pin

On the 8-pin version of this device only, the Debug pin shares function with the PA0 GPIO pin. This pin performs as a general purpose input pin on power-up, but the debug logic monitors this pin during the reset sequence to determine if the unlock sequence occurs. If the unlock sequence is present, the debug function is unlocked and the pin no longer functions as a GPIO pin. If it is not present, the debug feature is disabled until/unless another reset event occurs. For more details, see the On-Chip Debugger chapter on page 180.

Crystal Oscillator Override

For systems using a crystal oscillator, PA0 and PA1 are used to connect the crystal. When the crystal oscillator is enabled, the GPIO settings are overridden and PA0 and PA1 are disabled. See the Oscillator Control Register Definitions section on page 196 for details.

5V Tolerance

All six I/O pins on the 8-pin devices are 5V-tolerant, unless the programmable pull-ups are enabled. If the pull-ups are enabled and inputs higher than V_{DD} are applied to these parts, excessive current flows through those pull-up devices and can damage the chip.

Note:

In the 20- and 28-pin versions of this device, any pin which shares functionality with an ADC, crystal or comparator port is not 5 V-tolerant, including PA[1:0], PB[5:0] and PC[2:0]. All other signal pins are 5 V-tolerant and can safely handle inputs higher than V_{DD} except when the programmable pull-ups are enabled.

External Clock Setup

For systems using an external TTL drive, PB3 is the clock source for 20- and 28-pin devices. In this case, configure PB3 for alternate function CLKIN. Write the Oscillator Control (OSCCTL) Register such that the external oscillator is selected as the system clock. See the Oscillator Control Register Definitions section on page 196 for details. For 8-pin devices, use PA1 instead of PB3.

Table 15. Port Alternate Function Mapping (Non 8-Pin Parts)

Port	Pin	Mnemonic	Alternate Function Description	Alternate Function Set Register AFS1
Port A ^{1,2}	PA0	T0IN/T0OUT	Timer 0 Input/Timer 0 Output Complement	N/A
		Reserved		-
	PA1	T0OUT	Timer 0 Output	-
		Reserved		-
	PA2	DE0	UART 0 Driver Enable	-
		Reserved		-
	PA3	CTS0	UART 0 Clear to Send	-
		Reserved		
	PA4	RXD0/IRRX0	UART 0/IrDA 0 Receive Data	-
		Reserved		-
	PA5	TXD0/IRTX0	UART 0/IrDA 0 Transmit Data	-
		Reserved		-
	PA6	T1IN/T1OUT	Timer 1 Input/Timer 1 Output Complement	-
		Reserved		-
	PA7	T1OUT	Timer 1 Output	-
		Reserved		-

Notes:

- 1. Because there is only a single alternate function for each Port A pin, the Alternate Function Set registers are not implemented for Port A. Enabling alternate function selections automatically enables the associated alternate function. See the Port A-D Alternate Function Subregisters (PxAF) section on page 47 for details.
- 2. Whether PA0/PA6 takes on the timer input or timer output complement function depends on the timer configuration. See the <u>Timer Pin Signal Operation</u> section on page 84 for details.
- 3. Because there are at most two choices of alternate function for any pin of Port B, the Alternate Function Set Register AFS2 is not used to select the function. Alternate function selection must also be enabled. See the Port-A-D Alternate Function Subregisters (PxAF) section on page 47 for details.
- 4. V_{REF} is available on PB5 in 28-pin products and on PC2 in 20-pin parts.
- 5. Because there are at most two choices of alternate function for any pin of Port C, the Alternate Function Set Register AFS2 is not used to select the function. Alternate function selection must also be enabled. See the Port A–D Alternate Function Subregisters (PxAF) section on page 47 for details.
- 6. Because there is only a single alternate function for the Port PD0 pin, the Alternate Function Set registers are not implemented for Port D. Enabling alternate function selections automatically enables the associated alternate function. See the Port A–D Alternate Function Subregisters (PxAF) section on page 47 for details.

If TPOL is set to 0, the ratio of the PWM output High time to the total period is represented by:

PWM Output High Time Ratio (%) =
$$\frac{\text{Reload Value} - \text{PWM Value}}{\text{Reload Value}} \times 100$$

If TPOL is set to 1, the ratio of the PWM output High time to the total period is represented by:

PWM Output High Time Ratio (%) =
$$\frac{PWM \ Value}{Reload \ Value} \times 100$$

CAPTURE Mode

In CAPTURE Mode, the current timer count value is recorded when the appropriate external Timer Input transition occurs. The Capture count value is written to the Timer PWM High and Low Byte registers. The timer input is the system clock. The TPOL bit in the Timer Control Register determines if the Capture occurs on a rising edge or a falling edge of the Timer Input signal. When the Capture event occurs, an interrupt is generated and the timer continues counting. The INPCAP bit in TxCTL0 Register is set to indicate the timer interrupt is because of an input capture event.

The timer continues counting up to the 16-bit reload value stored in the Timer Reload High and Low Byte registers. Upon reaching the reload value, the timer generates an interrupt and continues counting. The INPCAP bit in TxCTL0 Register clears indicating the timer interrupt is not because of an input capture event.

Observe the following steps for configuring a timer for CAPTURE Mode and initiating the count:

- 1. Write to the Timer Control Register to:
 - Disable the timer
 - Configure the timer for CAPTURE Mode
 - Set the prescale value
 - Set the Capture edge (rising or falling) for the Timer Input
- 2. Write to the Timer High and Low Byte registers to set the starting count value (typically 0001H).
- 3. Write to the Timer Reload High and Low Byte registers to set the reload value.
- 4. Clear the Timer PWM High and Low Byte registers to 0000H. Clearing these registers allows the software to determine if interrupts were generated by either a capture event or a reload. If the PWM High and Low Byte registers still contain 0000H after the interrupt, the interrupt was generated by a Reload.

Bit	Description (Continued)
[6:5] TICONFIG	Timer Interrupt Configuration This field configures timer interrupt definition. 0x = Timer Interrupt occurs on all defined Reload, Compare and Input Events. 10 = Timer Interrupt only on defined Input Capture/Deassertion Events. 11 = Timer Interrupt only on defined Reload/Compare Events.
[4]	Reserved This bit is reserved and must be programmed to 0.
[3:1] PWMD	PWM Delay Value This field is a programmable delay to control the number of system clock cycles delay before the Timer Output and the Timer Output Complement are forced to their active state. 000 = No delay. 001 = 2 cycles delay. 010 = 4 cycles delay. 011 = 8 cycles delay. 100 = 16 cycles delay. 101 = 32 cycles delay. 110 = 64 cycles delay. 111 = 128 cycles delay.
[0] INPCAP	Input Capture Event This bit indicates if the most recent timer interrupt is caused by a Timer Input Capture Event. 0 = Previous timer interrupt is not a result of Timer Input Capture Event. 1 = Previous timer interrupt is a result of Timer Input Capture Event.

Timer 0-1 Control Register 1

The Timer 0–1 Control (TxCTL1) registers, shown in Table 51, enable and disable the timers, set the prescaler value and determine the timer operating mode.

Table 51. Timer 0-1 Control Register 1 (TxCTL1)

Bit	7	6	5	4	3	2	1	0
Field	TEN	TPOL	PRES TMODE					
RESET	0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Address		F07H, F0FH						

Bit	Description
[7]	Timer Enable
TEN	0 = Timer is disabled.
	1 = Timer enabled to count.

Table 75. ADC Data High Byte Register (ADCD_H)

Bit	7	6	5	4	3	2	1	0
Field	ADCDH							
RESET	Χ	Х	Х	Х	Χ	Х	Х	Х
R/W	R	R	R	R	R	R	R	R
Address	s F72H							
X = Undef	X = Undefined.							

Bit	Description
[7:0]	ADC Data High Byte
ADCDH	This byte contains the upper eight bits of the ADC output. These bits are not valid during a sin-
	gle-shot conversion. During a continuous conversion, the most recent conversion output is
	held in this register. These bits are undefined after a Reset.

ADC Data Low Byte Register

The ADC Data Low Byte (ADCD_L) Register contains the lower bits of the ADC output plus an overflow status bit. The output is a 13-bit two's complement value. During a single-shot conversion, this value is invalid. Access to the ADC Data Low Byte Register is read-only. Reading the ADC Data High Byte Register latches data in the ADC Low Bits Register.

Table 76. ADC Data Low Byte Register (ADCD_L)

Bit	7	6	5	4	3	2	1	0			
Field	ADCDL Reserved										
RESET	Х	Х	Х	Х	Х	Х	Х	Х			
R/W	R	R	R	R	R	R	R	R			
Address	F73H										
X = Undef	X = Undefined.										

Bit	Description
[7:3] ADCDL	ADC Data Low Bits These bits are the least significant five bits of the 13-bits of the ADC output. These bits are undefined after a Reset.

The following code example illustrates how to safely enable the comparator:

```
di
ld cmp0, r0 ; load some new configuration
nop
nop ; wait for output to settle
clr irq0 ; clear any spurious interrupts pending
ei
```

Comparator Control Register Definition

The Comparator Control Register (CMP0) configures the comparator inputs and sets the value of the internal voltage reference.

Table 77. Comparator Control Register (CMP0)

Bit	7	6	5	4	3	2	1	0				
Field	INPSEL	INNSEL		REF	Reserved (20-/28-pin) REFLVL (8-pin)							
RESET	0	0	0	1	0	1	0	0				
R/W	R/W	R/W	R/W	R/W	R/W	R/W						
Address			F90H									

Bit	Description
[7] INPSEL	Signal Select for Positive Input 0 = GPIO pin used as positive comparator input. 1 = Temperature sensor used as positive comparator input.
[6] INNSEL	Signal Select for Negative Input 0 = Internal reference disabled, GPIO pin used as negative comparator input. 1 = Internal reference enabled as negative comparator input.

Byte Write

To write a byte to the NVDS array, the user code must first push the address, then the data byte onto the stack. The user code issues a CALL instruction to the address of the byte-write routine (0x10B3). At the return from the sub-routine, the write status byte resides in working register R0. The bit fields of this status byte are defined in Table 106. The contents of the status byte are undefined for write operations to illegal addresses. Also, user code must pop the address and data bytes off the stack.

The write routine uses 13 bytes of stack space in addition to the two bytes of address and data pushed by the user. Sufficient memory must be available for this stack usage.

Because of the Flash memory architecture, NVDS writes exhibit a nonuniform execution time. In general, a write takes $251\,\mu s$ (assuming a 20MHz system clock). Every 400 to 500 writes, however, a maintenance operation is necessary. In this rare occurrence, the write takes up to 61 ms to complete. Slower system clock speeds result in proportionally higher execution times.

NVDS byte writes to invalid addresses (those exceeding the NVDS array size) have no effect. Illegal write operations have a $2\mu s$ execution time.

Table 106. Write Status Byte

Bit	7	6	5	4	3	2	1	0
Field		Rese	erved		RCPY	PF	AWE	DWE
Default Value	0	0	0	0	0	0	0	0

Bit	Description
[7:4]	Reserved These bits are reserved and must be programmed to 0000.
[3] RCPY	Recopy Subroutine Executed A recopy subroutine was executed. These operations take significantly longer than a normal write operation.
[2] PF	Power Failure Indicator A power failure or system reset occurred during the most recent attempted write to the NVDS array.
[1] AWE	Address Write Error An address byte failure occurred during the most recent attempted write to the NVDS array.
[0] DWE	Data Write Error A data byte failure occurred during the most recent attempted write to the NVDS array.

Bit	Description (Continued)
[3] WDFEN	Watchdog Timer Oscillator Failure Detection Enable 1 = Failure detection of Watchdog Timer oscillator is enabled. 0 = Failure detection of Watchdog Timer oscillator is disabled.
[2:0] SCKSEL	System Clock Oscillator Select 000 = Internal precision oscillator functions as system clock at 5.53MHz. 001 = Internal precision oscillator functions as system clock at 32kHz. 010 = Crystal oscillator or external RC oscillator functions as system clock. 011 = Watchdog Timer oscillator functions as system. 100 = External clock signal on PB3 functions as system clock. 101 = Reserved. 110 = Reserved. 111 = Reserved.

Table 128. eZ8 CPU Instruction Summary (Continued)

Assembly			ress de	_ Opcode(s)			Fla	ags			Fetch Cycle	Instr. Cycle
Mnemonic	Symbolic Operation	dst				ZSVDH					S	S
CALL dst	SP ← SP -2	IRR		D4	-	-	-	-	-	-	2	6
	@SP ← PC PC ← dst	DA		D6							3	3
CCF	C ← ~C			EF	*	-	-	-	-		1	2
CLR dst	dst ← 00H	R		В0	-	-	-	-	-	-	2	2
		IR		B1	-						2	3
COM dst	dst ← ~dst	R		60	-	*	*	0	-	_	2	2
		IR		61	-						2	3
CP dst, src	dst - src	r	r	A2	*	*	*	*	_	-	2	3
		r	lr	А3							2	4
		R	R	A4							3	3
		R	IR	A5	-						3	4
		R	IM	A6							3	3
		IR	IM	A7							3	4
CPC dst, src	dst - src - C	r	r	1F A2	*	*	*	*	_	_	3	3
		r	lr	1F A3	-						3	4
		R	R	1F A4	-						4	3
		R	IR	1F A5	-						4	4
		R	IM	1F A6	-						4	3
		IR	IM	1F A7	-						4	4
CPCX dst, src	dst - src - C	ER	ER	1F A8	*	*	*	*	_	-	5	3
		ER	IM	1F A9	-						5	3
CPX dst, src	dst - src	ER	ER	A8	*	*	*	*	_	_	4	3
		ER	IM	A9							4	3

Note: Flags Notation:

^{* =} Value is a function of the result of the operation.

⁻ = Unaffected.

X = Undefined.

^{0 =} Reset to 0.

^{1 =} Set to 1.

Table 128. eZ8 CPU Instruction Summary (Continued)

Assembly			ress ode	_ Opcode(s)			Fla	ags			Fetch Cycle	Instr. Cycle
Mnemonic	Symbolic Operation	dst	src	(Hex)	С	Z	S	٧	D	Н	S	S
SUB dst, src	dst ← dst – src	r	r	22	*	*	*	*	1	*	2	3
		r	lr	23	-						2	4
		R	R	24	-						3	3
		R	IR	25	-						3	4
		R	IM	26	-						3	3
		IR	IM	27	-						3	4
SUBX dst, src	dst ← dst – src	ER	ER	28	*	*	*	*	1	*	4	3
		ER	IM	29	-						4	3
SWAP dst	$dst[7:4] \leftrightarrow dst[3:0]$	R		F0	Χ	*	*	Χ	-	-	2	2
		IR		F1	-						2	3
TCM dst, src	(NOT dst) AND src	r	r	62	-	*	*	0	-	-	2	3
		r	lr	63	-						2	4
		R	R	64	-						3	3
		R	IR	65	-						3	4
		R	IM	66	-						3	3
		IR	IM	67	-						3	4
TCMX dst, src	(NOT dst) AND src	ER	ER	68	_	*	*	0	-	_	4	3
		ER	IM	69	-						4	3
TM dst, src	dst AND src	r	r	72	_	*	*	0	-	_	2	3
		r	lr	73	-						2	4
		R	R	74	-						3	3
		R	IR	75	-						3	4
		R	IM	76	-						3	3
		IR	IM	77	-						3	4

Note: Flags Notation:

^{* =} Value is a function of the result of the operation.

⁻ = Unaffected.

X = Undefined.

^{0 =} Reset to 0.

^{1 =} Set to 1.

Table 132. Power Consumption

		V _{DE}	= 2.7 V to 3	3.6 V		
Symbol	Parameter			Maximum Ext Temp ³	Units	Conditions
I _{DD} Stop	Supply Current in STOP Mode	0.1			μA	No peripherals enabled. All pins driven to V_{DD} or V_{SS} .
I _{DD} Halt	Supply Current in	35	55	65	μΑ	32kHz.
	HALT Mode (with all peripherals dis-	520			μΑ	5.5MHz.
	abled)	2.1	2.85	2.85	mA	20MHz.
I _{DD}	Supply Current in	2.8			mA	32kHz.
	ACTIVE Mode	4.5	5.2	5.2	mA	5.5MHz.
	(with all peripherals disabled)	5.5	6.5	6.5	mΑ	10MHz.
	_	7.9	11.5	11.5	mA	20MHz.
I _{DD} WDT	Watchdog Timer Supply Current	0.9	1.0	1.1	μΑ	
I _{DD}	Crystal Oscillator	40			μΑ	32kHz.
XTAL	Supply Current	230			μA	4MHz.
	-	760			μΑ	20MHz.
I _{DD} IPO	Internal Precision Oscillator Supply Current	350	500	550	μA	
I _{DD} VBO	Voltage Brown-Out and Low-Voltage	50			μA	For 20-/28-pin devices (VBO only); See Note 4.
	Detect Supply Current					For 8-pin devices; See Note 4.
I _{DD}	Analog to Digital	2.8	3.1	3.2	mA	32kHz.
ADC	Converter Supply	3.1	3.6	3.7	mA	5.5MHz.
	Current (with External Refer-	3.3	3.7	3.8	mA	10MHz.
	ence)	3.7	4.2	4.3	mA	20MHz.

Notes:

- 1. Typical conditions are defined as V_{DD} = 3.3V and +30°C.
- 2. Standard temperature is defined as $T_A = 0$ °C to +70°C; these values not tested in production for worst case behavior, but are derived from product characterization and provided for design guidance only.
- 3. Extended temperature is defined as $T_A = -40$ °C to +105°C; these values not tested in production for worst case behavior, but are derived from product characterization and provided for design guidance only.
- 4. For this block to operate, the bandgap circuit is automatically turned on and must be added to the total supply current. This bandgap current is only added once, regardless of how many peripherals are using it.

Table 139. Analog-to-Digital Converter Electrical Characteristics and Timing

 $V_{DD} = 3.0 \text{ V to } 3.6 \text{ V}$ $T_A = 0^{\circ}\text{C to } +70^{\circ}\text{C}$ (unless otherwise stated)

Symbol	Parameter	Minimum	Typical	Maximum	Units	Conditions
	Resolution	10		_	bits	
	Differential Nonlinearity (DNL)	-1.0	-	1.0	LSB ³	External V_{REF} = 2.0 V; $R_S \leftarrow 3.0 \text{ k}\Omega$
	Integral Nonlinearity (INL)	-3.0	-	3.0	LSB ³	External V_{REF} = 2.0 V; $R_S \leftarrow 3.0 \text{ k}\Omega$
	Offset Error with Calibration		<u>+</u> 1		LSB ³	
	Absolute Accuracy with Calibration		<u>+</u> 3		LSB ³	
V _{REF}	Internal Reference Voltage	1.0 2.0	1.1 2.2	1.2 2.4	V	REFSEL=01 REFSEL=10
V _{REF}	Internal Reference Variation with Temperature		<u>+</u> 1.0		%	Temperature variation with V _{DD} = 3.0
V _{REF}	Internal Reference Voltage Variation with V _{DD}		<u>+</u> 0.5		%	Supply voltage variation with T _A = 30°C
R _{RE-} FOUT	Reference Buffer Output Impedance		850		W	When the internal reference is buffered and driven out to the VREF pin (REFOUT = 1)
	Single-Shot Conversion Time	-	5129	-	Sys- tem clock cycles	All measurements but temperature sensor
			10258			Temperature sensor measurement

Notes:

- 1. Analog source impedance affects the ADC offset voltage (because of pin leakage) and input settling time.
- 2. Devices are factory calibrated at $V_{DD} = 3.3 \,\text{V}$ and $T_A = +30 \,^{\circ}\text{C}$, so the ADC is maximally accurate under these conditions.
- 3. LSBs are defined assuming 10-bit resolution.
- 4. This is the maximum recommended resistance seen by the ADC input pin.
- 5. The input impedance is inversely proportional to the system clock frequency.

On-Chip Debugger Timing

Figure 36 and Table 145 provide timing information for the DBG pin. The DBG pin timing specifications assume a 4 ns maximum rise and fall time.

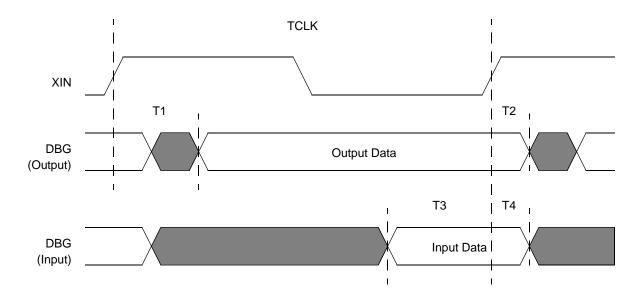


Figure 36. On-Chip Debugger Timing

Table 145. On-Chip Debugger Timing

		Delay (ns)	
Parameter	Abbreviation	Minimum	Maximum
DBG			
T ₁	X _{IN} Rise to DBG Valid Delay	_	15
T ₂	X _{IN} Rise to DBG Output Hold Time	2	_
T ₃	DBG to XIN Rise Input Setup Time	5	_
T ₄	DBG to XIN Rise Input Hold Time	5	_

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